

Sub c1

1. (Amended) An electronic circuit wiring interconnect package test and repair apparatus, comprising:

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at least one wiring analyzer to locate shorts between conductors, said conductors being on a surface of or embedded in a carrier substrate, said conductors being intended to interconnect components to be mounted on said carrier substrate to form a circuit, said carrier substrate being devoid of all said components;

a current source to provide current sufficient to remove said shorts; and

at least two probes to contact said conductors in a manner controlled by said wiring analyzer.

Sub c1

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7. (Amended) The test and repair apparatus of claim 1, wherein said at least one wiring analyzer additionally locates open circuits that are defects in said carrier substrate.